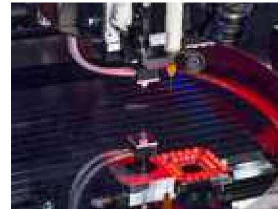
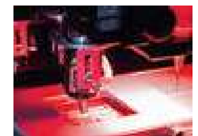
TRESKY AUTOMATION

Die Bonder

Flip Chip Bonder

Die Sorter





T-6000-L/G

Precision Die Attach Equipment with the most level of flexibility and customization

T-6000-L/G Flexible High Precision Automatic Die Bonder

The T-6000-L/G is an enhanced version of the proven T-6000-L series. A fully automated all-purpose system built on a sophisticated granite gantry and high precision motion control system. T-6000-L/G can be upgraded with new loader and unloader modules. The throughput for the latest advanced packaging applications has been extremely improved. With numerous available options, the T-6000-L/G can be customized to suit all market needs. This system offers our customers the opportunity to grow from a manual manufacturing process to a fully automated process without any additional hardware changes. Just a few software clicks will guide you through this process.

T-6000-L

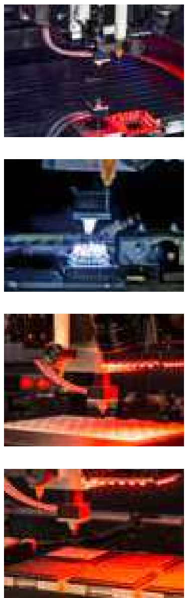
T-6000-L Flexible Automatic Die Bonder

The T-6000-L Die Bonder is a fully-automated all-purpose system for medium sized-, pilot- and R&D production. Equipped with linear motors and 0.1 µm resolution glass scales, this enables a movement precision of 8 µm @ 3Sigma. A force range of 15 g up to 800 g, combined with the large working area of 495 mmx 400 mm and wafer handling up to 8", offers a wide range of applications. With numerous available options, the T-6000-L can be customized to best suit all market needs.

T-8000-G

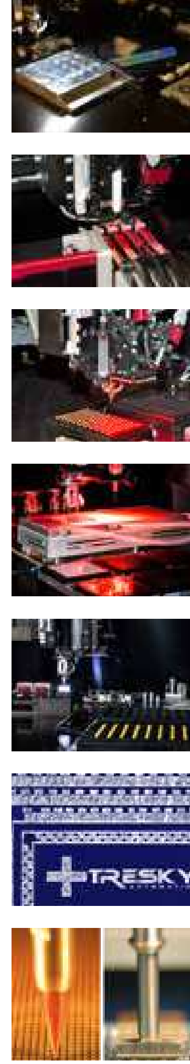
T-8000-G Flexible Automatic Die Bonder

The T-8000-G Die Bonder is a fully-automated all-purpose system built on a granite gantry .
Developed for a higher throughput and more accuracy, best fit for medium sized production.
This platform offers a large working area especially for 12" wafer handling. Open, with a wide range of applications and numerous available options, the T-8000-G can be customized to best suit all market needs.

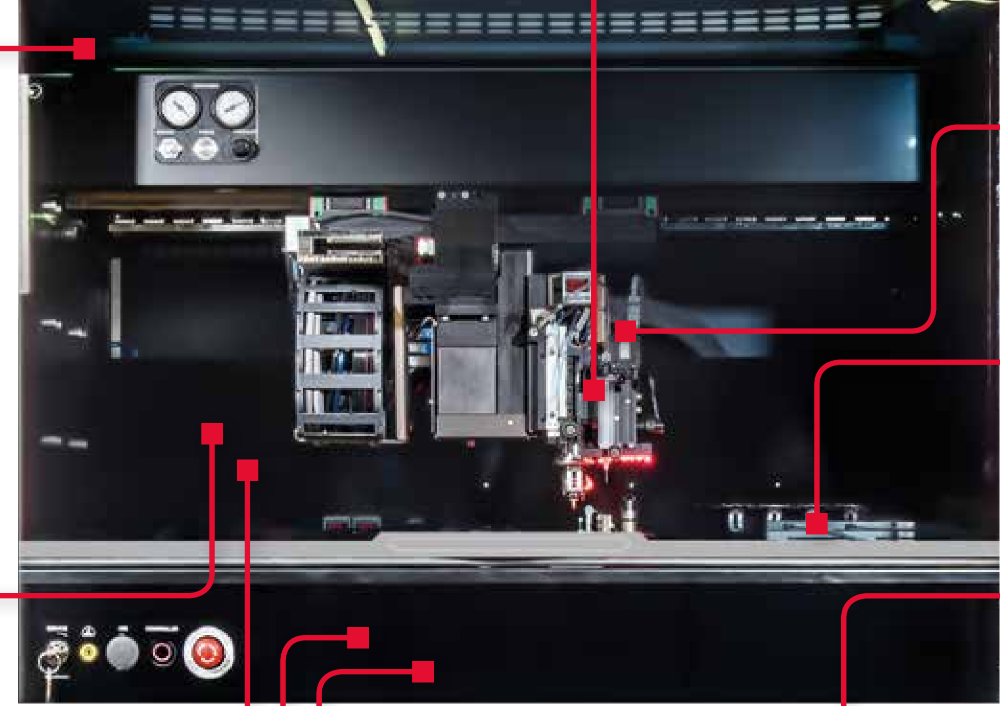


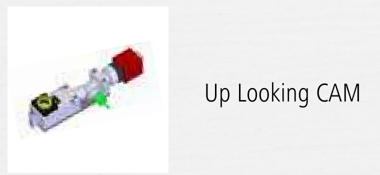
T-Series Options

Customized Precision Die Bonding Solution



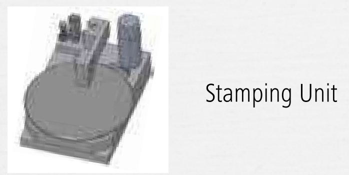
The enhanced T-6000-L/G Die Bonder equipped with a magazine loader / unloader system and a belt indexer for inline production.



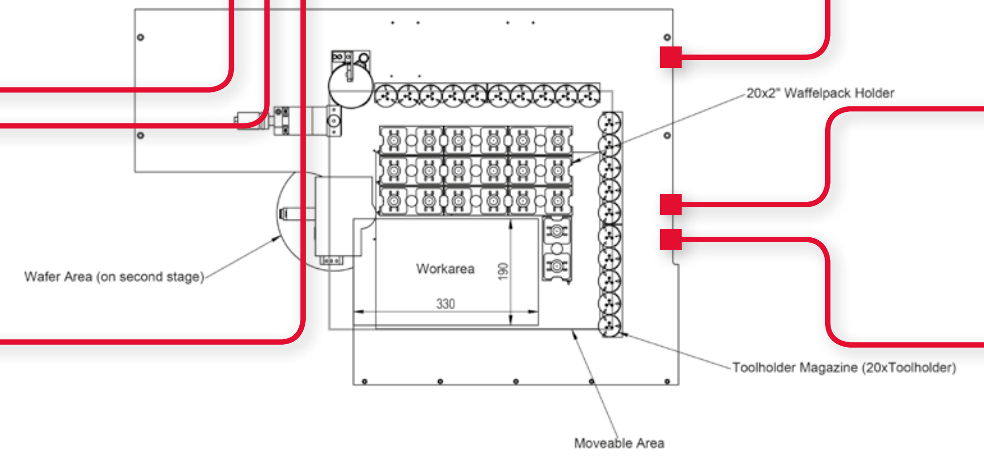

Up Looking CAM

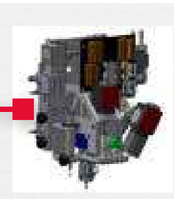
Wafer Handling Unit

Wafer Mapping

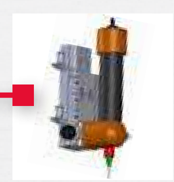

Stamping Unit

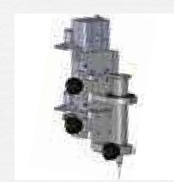
Die Flipping Unit

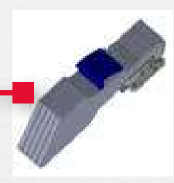



SL Bond Head

Advanced Bond Head


Micro Valve Dispenser

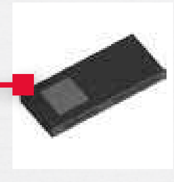

Time/ Pressure Dispenser


Feeder Unit

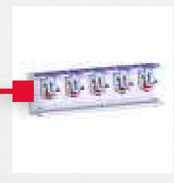
UV Indexer Unit

Inert Gas Heating Plate

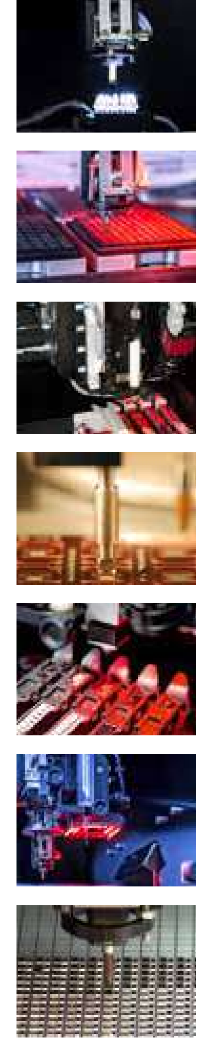
Shower Gas Heating Plate


Heating Plate

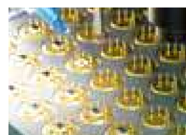
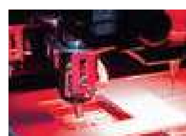
Speed Heating Plate


Tool Holder Bank

Customized Workholder Solutions

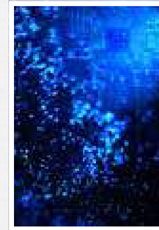


Applications

OPTO-ELECTRONICS

TRESKY's Die Bonder product line is well suited to provide comprehensive solutions for the Opto-electronic industry. Offering application flexibility including Epoxy Die Attach, Eutectic Die Attach, Flip Chip and UV cure solutions. TRESKY offers assembly solutions for Laser Diodes, Lens Assembly, Disk Drive Slider Assembly, Fiber Optic Assembly and MEMS applications.

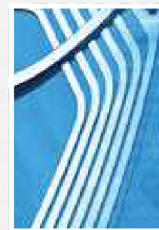


MEDICAL APPLICATIONS

The Medical Industry demands the highest level of accuracy, consistency and reliability of all its production equipment. Implantable devices for the human body have no room for failure and TRESKY engineers understand this critical industry. For this reason the TRESKY Die Bonders offer the flexibility and the critical controls required within the Medical Industry.

RF-WIRELESS-MICROWAVE

Managing die bond solutions for High Frequency Microwave Applications, Deep Housing Power Amplifiers as well as delicate GaN/GaAS devices is demanding for any Die Bond Equipment manufacturer. However, TRESKY's automated Die Bonder product line has several unique technology solutions that favor the successful assembly of these technology leading applications.

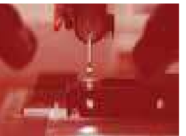


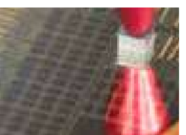
AUTOMOTIVE

The complexity of today's automotive electronics places new demands on the micro-electronic industry to provide robust solutions. This places unprecedented demands on the quality of assembly and the consistency of the die bond results. Bond line thickness and planarity are key items during the manufacturing process. TRESKY understands this industry and its critical needs thus the Die Bonders are designed to provide solutions within volume production.

	T-6000-L/G	T-6000-L	T-8000-G
XY-Movement (placement stage)	450 mm x 400 mm	495 mm x 400 mm	700 mm x 500 mm
XY-Movement (wafer stage)	220 mm x 220 mm	220 mm x 220 mm	305 mm x 305 mm
Z-Movement	100 mm	100 mm	120 mm
Spindle Rotation	200° (100° with heated tools)	200° (100° with heated tools)	200° (100° with heated tools)
Bond Force (standard range)	15 g - 800 g (optional up to 5.000 g)	15 g - 800 g (optional up to 5.000 g)	15 g - 800 g (optional up to 5.000 g)
UPH	2200*	2000*	2800*
Placement Accuracy	2,5 µm @ 3Sigma*	8 µm @ 3Sigma*	2,5 µm @ 3Sigma*
Axis Resolution	XYZ: 0.1 µ, Theta: 0.02 µ	XYZ: 0.1 µ, Theta: 0.02 µ	XYZ: 0.1 µ, Theta: 0.02 µ
Min./ Max. component size	100 µm/ 20 mm**	100 µm/ 20 mm**	100 µm/ 20 mm**
Wafer Pickup	2" to 8"	2" to 8"	2" to 12"
Connections	Compressed dry air 6 bar/ Vacuum 0.9 bar (abs.) min. 4.5 m³/h	Compressed dry air 6 bar/ Vacuum 0.9 bar (abs.) min. 4.5 m³/h	Compressed dry air 6 bar/ Vacuum 0.9 bar (abs.) min. 4.5 m³/h
Dimensions	1360 mm x 995 mm x 1690 mm	1360 mm x 995 mm x 1690 mm	1750 mm x 1050 mm x 1820 mm
Weight	1300 kg (approx.)	720 kg (approx.)	1550 kg (approx.)
Voltage	220 V-260 V, 50 Hz, 2.3 kW (10 A) 1phase	220 V-260 V, 50 Hz, 2.3 kW (10 A) 1phase	220 V-260 V, 50 Hz, 3.7 kW (16 A) 1phase
Environment	Room temp: 22°C +/- 2°C	Room temp: 22°C +/- 2°C	Room temp: 22°C +/- 2°C
Humidity	50%, +/-5%	50%, +/-5%	50%, +/-5%

* Process depending /** Other dimensions on request | Note: All specifications are subject to change without notice





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Indexer
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Customisation
Component Handling
Epoxy Die Bonding
Lifter
interconnect of microelectronic
Laser Diode Assembly
Multi chip
placing
IC Assembly
high-performance
Vison Alignment